



3.2 x 2.5mm Crystal AEC-Q200 Qualified

Helping Customers Innovate, Improve & Grow

Table 1. Electrical Performance								
Parameter	Symbol	Min.	Тур	Max	Units			
Nominal Frequency ¹	F _{NOM}		24.305		MHz			
Mode		Fun	damental, AT -	Cut				
Operating Temperature Range	T _{OP}	-40/105 °C						
Stability Over T _{OP} ²	F _{STAB}		±15					
Frequency Tolerance ²	F _{TOL}			±10	ppm			
Load Capacitance	C _L		7		pF			
Shunt Capacitance	C _o			1.5	pF			
Motional Capacitance	C ₁		4.7		fF			
ESR			25	50	ohms			
Drive Level			10	200	uW			
Aging / 1st year (at 25 °C) 10 years (at 25 °C)	F _{AGE}			±5 ±15	ppm			
Insulation Resistance		500			MOhm			
Storage Temperature	T _{sto}	-40		125	°C			

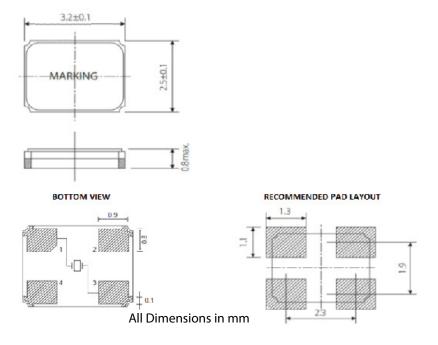
Notes:

- 1. Referenced to the Frequency at 25 $^{\circ}$ C.
- 2. Frequency measured at 25 °C \pm 3 °C.

Product is compliant to RoHS directive and fully compatible with lead free assembly.



Package Drawing



Marking

XXMXX

VYYMC

where

XXMXX = Frequency

V = VECTRON

YY = Year (Ex 19: 2019)

M = Month (A:Jan, B: Feb, C: March...)

C = Manufacturing Location

able 2. Environmental Compliance						
Parameter	Conditions					
High Temperature Exposure (Storage)	MIL-STD-202, Method 108 1000 hours at 85°C					
Temperature Cycle	JESD22, Method JA-104 1000 cycles, -40/85°C 30 min maximum dwell time at each temperature extreme. 1 minute maximum transition time.					
Biased Humidity	MIL-STD-202 Method 103 1000 hours 85°C / 85 % RH.					
Operational Life	MIL-STD-202 Method 108 Note: 1000 hrs @ 125°C.					
External Visual	MIL-STD-883 Method 2009					
Physical Dimensions	JESD22 Method JB-100 Verify physical dimensions to the applicable device detail specification.					
Resistance to Solvents	MIL-STD-202 Method 215 Note: Also aqueous wash chemical - OKEM clean or equivalent. Do not use banned solvents.					
Mechanical Shock	MIL-STD-202 Method 213 Condition C					
Vibration	MIL-STD-202 Methood 2004 5g's for 20 minutes, 12 cycles each of 3 orientations, 10-2000 Hz.					
Resistance to Soldering Heat	MIL-STD-202 Method 210 Condition B					
Solderability	J STD-002					
Flammability	UL-94 V-0 or V-1					
Board Flex	AEC-Q200-005					
Terminal Strength	AEC-Q200-005					
Moisture Sensitivity Level	MSL1					
Contact Pads	Gold (0.2 um min) over nickel					
Weight	20 mg					

Reliability & IR Compliance

Solderprofile:

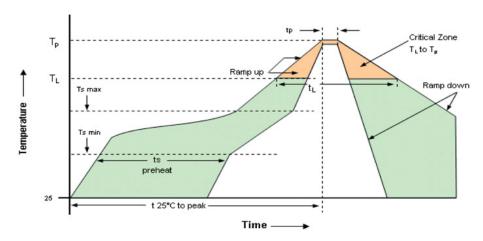
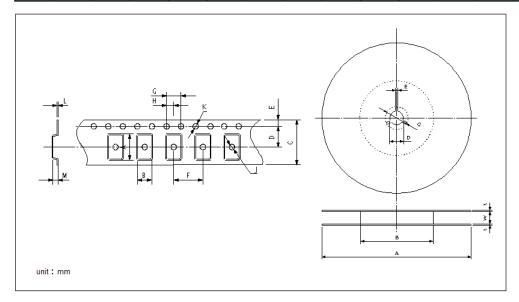


Table 3: Reflow Profile							
Parameter	Symbol	Value					
PreHeat Time Ts-min Ts-max	t _s	60 sec Min, 260 sec Max 150°C 200°C					
Ramp Up	R _{UP}	3 °C/sec Max					
Time Above 217 °C	t _L	60 sec Min, 150 sec Max					
Time To Peak Temperature	T_{AMB-P}	480 sec Max					
Time at 260 °C	t _P	30 sec Max					
Ramp Down	$R_{_{\mathrm{DN}}}$	6 °C/sec Max					

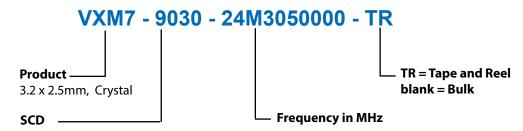
Tape & Reel

Table	Table 4. Tape and Reel Dimensions (mm)																	
Tape Reel																		
Α	В	С	D	Е	F	G	Н	J	К	L	М	Α	В	С	D	Е	W	Т
3.6	2.9	8.0	3.5	1.75	4.0	4.0	2.0	0.5	1.55	0.25	1.0	180	60	21.0	13.0	2.0	9.0	2.0



3K pieces per reel

Ordering Information



Revision History

Revision Date	Approved	Description
March 17, 2020	FB	rev0.1 Initial

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